

What is claimed is:

SUB
A1

1. A multilayer ceramic capacitor comprising internal electrode layers and dielectric layers, wherein an average particle diameter (R), in a direction parallel with said internal electrode layers, in dielectric particles constituting said dielectric layers is larger than a thickness (d) of said dielectric layer.

10 2. The multilayer ceramic capacitor as set forth in claim 1, wherein a ratio (R/d) between said average particle diameter (R) and the thickness (d) of said dielectric layer satisfies $1 < R/d < 3$.

15 2.3. The multilayer ceramic capacitor as set forth in claim 1, wherein a main component of said internal electrode layers is Ni or Cu.

4. The multilayer ceramic capacitor as set forth in claim 2 wherein a main component of said internal electrode layers is Ni or Cu.

SUB
A2

20 5. The multilayer ceramic capacitor as set forth in claim 3, wherein Fe is segregated in said internal electrode layer.

6. The multilayer ceramic capacitor as set forth in claim 4, wherein Fe is segregated in said internal electrode layer.

25 7. The multilayer ceramic capacitor as set

0986575-052901

05663950

5

10

15

20

25

13. The multilayer ceramic capacitor as set forth in claim 2, wherein said dielectric particles

have a core-shell structure.

SUB
A3

14. The multilayer ceramic capacitor as set forth in claim 1, wherein said dielectric layer is comprised of dielectric particles, a grain boundary and grain boundary phase, a segregation phase exists in said grain boundary phase, and said segregation phase contains at least two kinds of elements selected from Mn, Y, Si, Ca, V and W.

15. The multilayer ceramic capacitor as set forth in claim 2, wherein said dielectric layer is comprised of dielectric particles, a grain boundary and grain boundary phase, a segregation phase exists in said grain boundary phase, and said segregation phase contains at least two kinds of elements selected from Mn, Y, Si, Ca, V and W.

16. A production method of a multilayer ceramic capacitor, comprising the steps of:

firing a green chip to be a capacitor element body comprising dielectric layers and internal electrode layers in a reducing atmosphere; and

performing heat processing under an atmosphere of which oxygen partial pressure is higher than the reducing atmosphere;

wherein:

5

10

15

~~Add C2~~